

**Qualification Results Summary of LTM4671 with Sumitomo G311E mold compound**

| QUALIFICATION STATUS – LTM4671 BGA               |                            |             |         |
|--|----------------------------|-------------|---------|
| TEST   | SPECIFICATION              | SAMPLE SIZE | RESULTS |
| Unbiased Highly Accelerated Stress Test (UHAST)* | JEDEC <i>JESD22-A102</i>   | 1*77        | Pass    |
| Temperature Cycle (TC)*                          | JEDEC <i>JESD22-A104</i>   | 1*77        | Pass    |
| Thermal Shock (TS)*                              | JEDEC <i>JESD22-A106</i>   | 1*77        | Pass    |
| Solder Heat Resistance (SHR)*                    | JEDEC/IPC <i>J-STD-020</i> | 2*231       | Pass    |

\*Preconditioned per JEDEC/IPC J-STD-020 MSL3 (@245C)